

Die Bonder and/or Wire Bonder with a Suction Device for Pulling Flat and Holding Down a Curved Substrate

ABSTRACT

A Die Bonder or Wire Bonder has a suction device for pulling flat and holding down a curved substrate (3) equipped with or to be equipped with a semiconductor chip onto a supporting surface (2) of a plate (1). The plate (1) contains at least one cavity (7) open towards the supporting surface (2) in which there is a vacuum gripper (8.1; 8.2; 8.3; 8.4) made out of flexible material, whereby the vacuum gripper (8.1; 8.2; 8.3; 8.4) is lowerable into the cavity (7) during transport of the substrate (3) and which is raisable above the level of the supporting surface (2) to apply suction to the substrate (3).

(Fig. 1)